tp

## Lecture 7-3 MOSIS/SCNA Design Example-

## **Piezoresistive type Accelerometer III**

## $\mathbf{V}_{\mathbf{0}}$ b/2 V. V+ $L_{b}$ 5.98 µm Lg 3.83 µm over glass=1 3.35 µm met2=1.15 ox2=0.65 met1=0.6 o-g ox1=0.85 ·ox2 a poly2=0.4 poly ox1=0.08 ox1 Poly=0.4 fox fox=0.85

**Example of real # plugging in:** 

A design for the accelerometer:

**Proof mass:** 

 $L_p=W=500 \ \mu m, t_p=5.98 \ \mu m, \rho \sim 2.5 \ g/cm^3$ 

**Cantilever beam:** 

 $L_b=b/2=20 \ \mu m$ , a=3.58  $\mu m$ , z~0.865  $\mu m$ , E~10<sup>11</sup> Pa

Piezoresistor (polysilicon): G<sub>gauge</sub>~20, R<sub>0</sub>=1 kΩ, L<sub>g</sub>=20 μm NTHU ESS5850 F. G. Tseng

1. Proof mass:  $m = L_p \times W \times t_p \times \rho = 3.58$  µgm

2. Moment: 
$$M = mg_{ace}(L_b + \frac{L_p}{2}) = 0.9667g_{ace} pNm$$

3. Momentum of inertia: 
$$I = \frac{a^3b}{12} = 1.53 \times 10^{-22} m^4$$

4. Strain: 
$$\mathcal{E}_{\text{max}} = \frac{zM}{EI} = 6g_{ace} \times 10^{-8}$$
 100%

5. Resistance change: 
$$\frac{\Delta R}{R} = G_{guage} (1 - \frac{L_g}{2L_b}) \varepsilon_{max} = 6g_{ace} \times 10^{-7}$$

6. Voltage change: 
$$\Delta V = V_e \frac{-\Delta R}{2R} = 0.3 g_{ace} V_e \quad \mu V$$

7. Responsivity: 
$$R_{ace} = \frac{\Delta V}{q} = 3 \cdot V_e \quad \mu V / g$$
,

$$g_{ace} = q \times 9.8 \quad \frac{m}{s^2}$$

## 8. Maximum deflection:

$$y(L_b + L_p) = y(L_b) + \theta(L_b)L_p = 7.9 \times 10^{-2} / g$$
 µm  
Spring constant:  $K = \frac{3EI}{L_b^3} = 5737.5$  N/m

**10.Squeeze film damping:** 

9.

$$c = \frac{3\pi\mu R^4}{2d^3} \sim 3.397 \times 10^{-7} (d \sim 100\,\mu m, R \sim 250\,\mu m)$$

# **11.Resonant Frequency:**

$$\omega_n = \sqrt{\frac{K}{m}} = 1.27 \times 10^6 \, rad \, / \, s \Longrightarrow f_n = 201 \quad kHz$$

12.Noise:

a. TNEA: 
$$\overline{a}_n = \sqrt{\frac{4kT\omega_0}{MQ}} = 2.095 \times 10^{-5} \quad \frac{m}{s^2} \frac{1}{\sqrt{Hz}}$$

- b. Johnson Noise:  $\overline{v}_n = \sqrt{4kTRf} = 4.07 \cdot \sqrt{f} \quad nV$
- c. Total Noise:

$$\overline{a}^{2}_{ntotal} = \overline{a}^{2}_{n} * f + (\frac{\overline{v}_{n1}}{R_{ace}})^{2} + (\frac{\overline{v}_{n2}}{R_{ace}})^{2} + (\frac{\overline{v}_{n3}}{R_{ace}})^{2} + (\frac{\overline{v}_{n4}}{R_{ace}})^{2}$$
$$\Rightarrow \overline{a}_{ntotal} = \sqrt{4.41 \times 10^{-10} f + 4 * 1.84 \times 10^{-6} \cdot f / V_{e}^{2}} g$$

For f=201 kHz and V<sub>e</sub>=10 Volts,

$$\overline{a}_{ntotal} = 0.244g$$

## 13.Dynamic range:

a. Upper limit:

$$a_{upper} = \varepsilon_{fracture}(0, \frac{a}{2}) \frac{EI}{\frac{a}{2}m(\frac{L_p}{2} + L_b)} = 88428.4m/s^2 = 9023.3g$$

(here assume  $\varepsilon_{\text{fracture}}=1\%$ )

**b.** Lower limit:

$$a_{lower} = \overline{a}_{ntotal} = 0.244g$$

Dynamic range is around 3.7 \*10<sup>4</sup>

14.Peak deflection under 9023.3 g:

712.84 µm

# **Prospects for Final project and Presentations**

## 1. # of persons in a group: 5-6 (total group:10)

#### 2. final presentation (each group)

- a. 12 minutes on presentation, 3 minutes for questions, prepare 10 transparencies.
- b. Focus on your detail design, process, expect results, and testing methods.
- c. Hand in one copy of the transparency
- d. Write down the contribution of each person in this group on a cover sheet and have the sheet signed by each person.
- 3. Final report (each group)
  - a. Follow the two-column format of Tansducers'01 paper attached (in Chinese or English).
  - b. Including, not limiting to: abstract, introduction, design, fabrication process, expect result, testing method, difficulties/limitations, and reference. Page#: either 4 or 6 pages. No exception.
  - c. Hand in the report with the reference you did not include in the first presentation, and one sheet to describe the name and function of each layout layer.
  - d. Also Hand in a disk containing (or email in) the .tdb file of your design layout.
  - e. Write down the contribution of each person in this group on a cover sheet and have the sheet signed by each person.

#### 4. Grading for presentation and final report

- a. Creativity: 30%
- b. Preparation: 30%
- c. Working possibility 20%
- d. Presentation/writing 20%
- e. Extra 10% for question asking!!

6. Topics:

**Option1. Design a rate gyro with the following specs:** 

- a. Bandwidth: DC to 100 Hz
- b. Noise equivalent rotation: 1 rad/sec
- c. Use either CMOS or MCNC/MUMPS/LIGA/DRIE process
- d. Design a testing structure to give a 1 rad/sec rate on chip

**Option2. Design a Seismometer with the following specs:** 

- a. Bandwidth: 10 Hz to 1 kHz
- b. Range: 0.01g to 10g
- c. Noise equivalent acceleration: 0.005g
- d. Thermal stability: less than 1% error from -20 to 100 °C
- e. Use CMOS or MCNC/MUMPS/LIGA/DRIE process
- f. Design a testing structure to give a 0.1g acceleration on chip
- g. Protection structure for sensor over range protection
- **Option3. Design a accelerometer (for air bag application) with the following specs:** 
  - a. Bandwidth: DC to 1 kHz
  - b. Range: -50g to 50g
  - c. Noise equivalent acceleration: 0.4g
  - d. Thermal stability: less than 1% error from -50 to 100 °C
  - e. Use CMOS or MCNC/MUMPS/LIGA/DRIE process
  - f. Design a testing structure to give a 1g acceleration on chip
- **Option4.** Design a pressure sensor with the following specs:
  - a. Bandwidth: DC to 1 kHz
  - b. Pressure Range: 100 Pa to 10 ATM
  - c. Noise equivalent pressure: 50 Pa
  - d. Thermal stability: less than 1% error from -50 to 100 °C
  - e. Use CMOS process
- **Option5. Design a electrically controlled mirror with the following specs:** 
  - a. Mirror perpendicular to the substrate to within 1 degree
  - b. Mirror can either translate 200 microns in 2  $\mu m$  steps or

less, or rotate 180 degree in 2 degree steps or less.

- c. Step speed larger than 100 Hz
- d. Use MCNC/MUMPS process

# **Option6. Design a electrically controlled actuator with the following specs:**

- a. Force output larger than 10 µN.
- b. Displacement larger than 10 µm.

**Option7.Choose your own topic** 

- a. Decide your own specs (draft) and discuss with me before 11/26/2001
- b. Decide your own process flow and discuss with me before 12/19/2001